



For immediate release

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Canadian Engineering Memorial Foundation Announcement:

New Vale Inco Undergraduate Scholarships added to already extensive 2009 scholarship program

(Renfrew, Ontario): Three more Canadian women will have their dream of becoming an engineer supported by a prestigious scholarship thanks to the Canadian Engineering Memorial Foundation's partnership with Vale Inco.

New for 2009, Vale Inco has joined with the Foundation to offer three \$10,000 undergraduate engineering scholarships to women studying in an accredited program in Canada. Each scholarship also comes with a summer job opportunity.

These new scholarships will mean a total of 14 scholarships will be offered by the Foundation for women in engineering at the undergraduate, master's and PhD levels this year.

Undergraduates can apply to: the five \$5,000 CEMF Undergraduate Engineering Scholarships with one scholarship given in each region of Canada – Atlantic, Quebec, Ontario, Prairies and British Columbia; the two \$2,500 IBM Undergraduate Engineering Scholarships available for women studying in an accredited electrical, computer, software or computer systems design engineering program (these scholarships also come with a summer job opportunity); or the \$5,000 AMEC Aboriginal Undergraduate Engineering Scholarship offered to a Canadian Aboriginal woman studying engineering in an accredited program.

At the master's level, there is the \$10,000 Vale Inco Master's Engineering Scholarship and the \$10,000 AMEC Master's Engineering Scholarship – both are open to women studying in any field of engineering. Both scholarships come with a summer job opportunity.

Finally, there is the exceptional \$15,000 Claudette MacKay-Lassonde Scholarship offered to a woman working on her PhD in engineering.

All scholarships are awarded based on leadership, extracurricular activities and the ability to act as a role model for other women to pursue a career in engineering, rather than on academic achievement.

Scholarship informational packages and posters will be sent to all universities, Deans, engineering organizations and clubs, WISE organizations, provincial associations and other stakeholders. Please contact CEMF if you wish to receive a package.

All applications and criteria are available now online at www.cemf.ca. Deadline for application is January 16, 2009.